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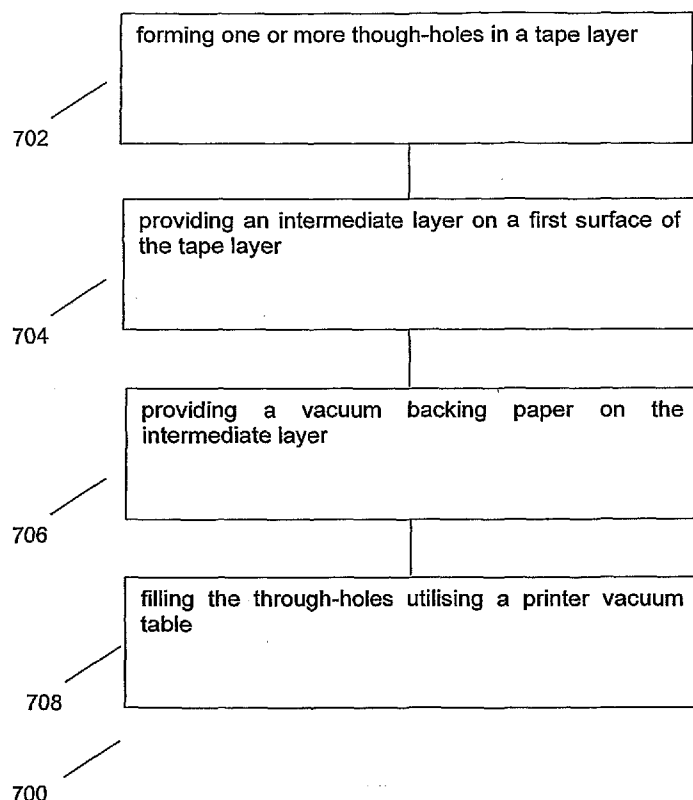
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(54) Title: LTCC SUBSTRATE STRUCTURE



(57) Abstract: A method of forming a low temperature co-fired ceramic (LTCC) based substrate structure having one or more through holes, with an aspect ratio of a thickness of the LTCC substrate to a lateral dimension of the through-holes smaller than about 1, the method comprising the steps of forming the through-holes in a tape layer; providing an intermediate layer on a first surface of the tape layer; providing a vacuum backing paper on the intermediate layer; and filling the through-holes utilising a printer vacuum table.

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